

PATENT WITHDRAWAL NOTICE

DATE WITHDRAWN	WITHDRAWAL NUMBER
4/17/09	17124

The following application has been **WITHDRAWN** from the
Tuesday, May 05, 2009 issue.

SERIAL NO.	PATENT NUMBER
10/591,455	7,528,193
DRAWINGS	CLASS
000	525/064

TITLE
THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE COMPRISING THE SAME

NAME AND ADDRESS
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REASON FOR WITHDRAWAL
Office of Petitions granted applicant's request to withdraw patent from issue.

APPROVED

/Kimberly Terrell/, Manager
Patent Publication Branch
Office of Data Management